A Product Line of
Diodes Incorporated

PI6C20400B

1:4 Clock Driver for Intel PCIe® 3.0 Chipsets

Features

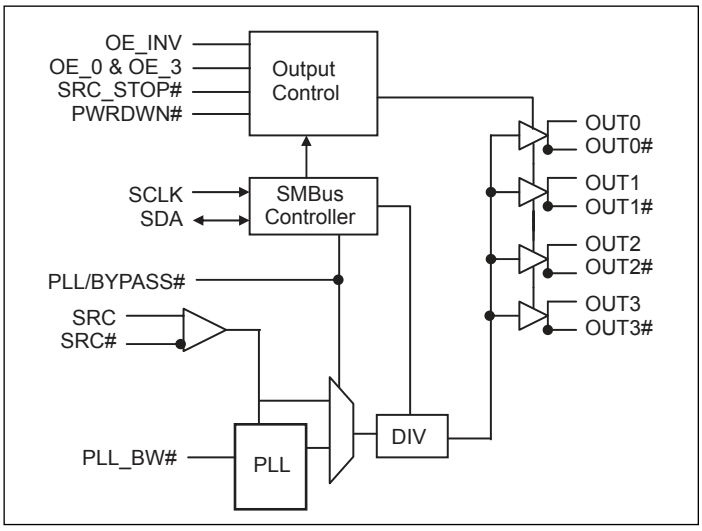
- Phase jitter filter for PCIe 3.0 application
- Four Pairs of Differential Clocks
- Low skew < 50ps
- Low jitter < 50ps cycle-to-cycle
- < 1 ps additive RMS phase jitter
- Output Enable for all outputs
- Outputs tristate control via SMBus
- Programmable PLL Bandwidth
- 100 MHz PLL Mode operation
- 100 - 400 MHz Bypass Mode operation
- 3.3V Operation
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.
  https://www.diodes.com/quality/product-definitions/
- Packaging (Pb-free and Green):
  -28-Pin, SSOP (H28)
  -28-Pin, TSSOP (L28)

Description

The PI6C20400B is a PCIe 3.0 compliant high-speed, low-noise differential clock buffer designed to be companion to PCIe 3.0 clock generator. It is backward compatible with PCIe 1.0 and 2.0 specification.

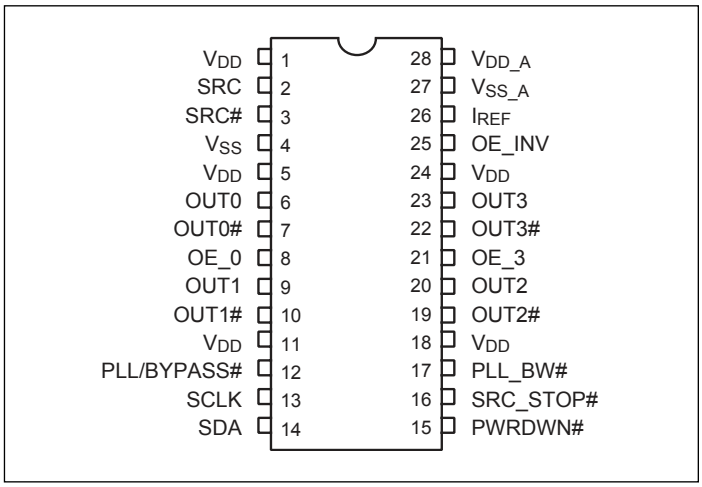
The device distributes the differential SRC clock from PCIe 3.0 clock generator to four differential pairs of clock outputs either with or without PLL. The clock outputs are controlled by input selection of SRC_STOP#, PWRDWN# and SMBus, SCLK and SDA. When input of either SRC_STOP# or PWRDWN# is low, the output clocks are Tristated. When PWRDWN# is low, the SDA and SCLK inputs must be Tri-stated.

Block Diagram



Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Pin Configuration



Pin Description

Pin#	Pin Name	Type	Description
2, 3	SRC & SRC#	Input	0.7V Differential SRC input from PI6C410 clock synthesizer
8, 21	OE_0 & OE_3	Input	3.3V LVTTL input for enabling outputs, active high. OE_0 for OUT0 / OUT0# OE_3 for OUT3 / OUT3#
25	OE_INV	Input	3.3V LVTTL input for inverting the OE, SRC_STOP# and PWRDWN# pins. When 0 = same stage When 1 = OE_0, OE_3, SRC_STOP#, PWRDWN# inverted.
6, 7, 9, 10, 19, 20, 22, 23	OUT[0:3] & OUT[0:3]#	Output	0.7V Differential outputs
12	PLL/BYPASS#	Input	3.3V LVTTL input for selecting fan-out of PLL operation.
13	SCLK	Input	SMBus compatible SCLOCK input
14	SDA	I/O	SMBus compatible SDATA
26	IREF	Input	External resistor connection to set the differential output current
16	SRC_STOP#	Input	3.3V LVTTL input for SRC stop, active low
17	PLL_BW#	Input	3.3V LVTTL input for selecting the PLL bandwidth
15	PWRDWN#	Input	3.3V LVTTL input for Power Down operation, active low
1, 5, 11, 18, 24	V_{DD}	Power	3.3V Power Supply for Outputs
4	VSS	Ground	Ground for Outputs
27	VSS_A	Ground	Ground for PLL
28	VDD_A	Power	3.3V Power Supply for PLL

Serial Data Interface (SMBus)

This part is a slave only SMBus device that supports indexed block read and indexed block write protocol using a single 7-bit address and read/write bit as shown below.

Address Assignment

A6	A5	A4	A3	A2	A1	A0	W/R
1	1	0	1	1	1	0	0/1

Data Protocol

1 bit	7 bits	1	1	8 bits	1	8 bits	1	8 bits	1		8 bits	1	1 bit
Start bit	Slave Addr	R/W	Ack	Register offset	Ack	Byte Count = N	Ack	Data Byte 0	Ack	…	Data Byte N - 1	Ack	Stop bit

Notes:

1. Register offset for indicating the starting register for indexed block write and indexed block read. Byte Count in write mode cannot be 0.

Data Byte 0: Control Register

Bit	Descriptions	Type	Power Up Condition	Output(s) Affected	Source Pin
0	Outputs Mode 0 = Divide by 2 1 = Normal	RW	1 = Normal	OUT[0:3], OUT[0:3]#	NA
1	PLL/BYPASS# 0 = Fanout 1 = PLL	RW	1 = PLL	OUT[0:3], OUT[0:3]#	NA
2	PLL Bandwidth 0 = High Bandwidth, 1 = Low Bandwidth	RW	1 = Low	OUT[0:3], OUT[0:3]#	NA
3	Reserved				NA
4	Reserved				NA
5	Reserved				NA
6	SRC_STOP# 0 = Driven when stopped 1 = Tristate	RW	0 = Driven when stopped	OUT[0:3], OUT[0:3]#	NA
7	PWRDWN# 0 = Driven when stopped 1 = Tristate	RW	0 = Driven when stopped	OUT[0:3], OUT[0:3]#	NA

Data Byte 1: Control Register

Bit	Descriptions	Type	Power Up Condition	Output(s) Affected	Source Pin
0	Reserved				NA
1	OUTPUTS enable 1 = Enabled 0 = Disabled	RW	1 = Enabled	OUT0, OUT0#	NA
2		RW	1 = Enabled	OUT1, OUT1#	NA
3	Reserved				NA
4	Reserved				NA
5	OUTPUTS enable 1 = Enabled 0 = Disabled	RW	1 = Enabled	OUT2, OUT2#	NA
6		RW	1 = Enabled	OUT3, OUT3#	NA
7	Reserved				NA

Data Byte 2: Control Register

Bit	Descriptions	Type	Power Up Condition	Output(s) Affected	Source Pin
0	Reserved				NA
1	Allow control of OUTPUTS with assertion of SRC_STOP# 0 = Free running 1 = Stopped with SRC_Stop#	RW	0 = Free running	OUT0, OUT0#	NA
2		RW	0 = Free running	OUT1, OUT1#	NA
3	Reserved				NA
4	Reserved				NA
5	Allow control of OUTPUTS with assertion of SRC_STOP# 0 = Free running 1 = Stopped with SRC_Stop#	RW	0 = Free running	OUT2, OUT2#	NA
6		RW	0 = Free running	OUT3, OUT3#	NA
7	Reserved				NA

Data Byte 3: Control Register

Bit	Descriptions	Type	Power Up Condition	Output(s) Affected	Source Pin
0	Reserved	RW			
1		RW			
2		RW			
3		RW			
4		RW			
5		RW			
6		RW			
7		RW			

Data Byte 3: Control Register

Bit	Descriptions	Type	Power Up Condition	Output(s) Affected	Pin
0	Pericom ID	R	0	NA	NA
1		R	0	NA	NA
2		R	0	NA	NA
3		R	0	NA	NA
4		R	0	NA	NA
5		R	1	NA	NA
6		R	0	NA	NA
7		R	0	NA	NA

Functionality

PWRDWN#	OUT	OUT#	SRC_Stop#	OUT	OUT#
1	Normal	Normal	1	Normal	Normal
0	I_{REF} × 2 or Float	Low	0	I_{REF} × 6 or Float	Low

Power Down (PWRDWN# assertion)

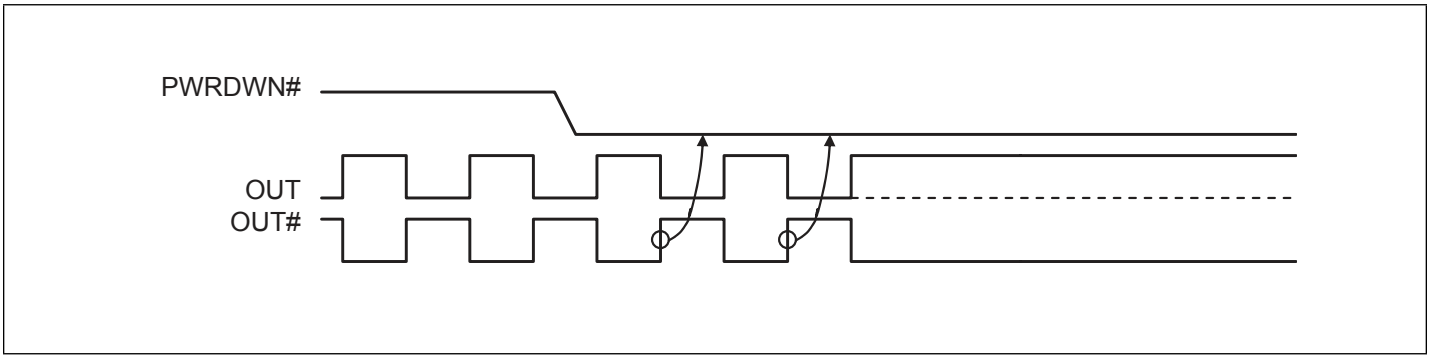


Figure 1. Power down sequence

Power Down (PWRDWN# De-assertion)

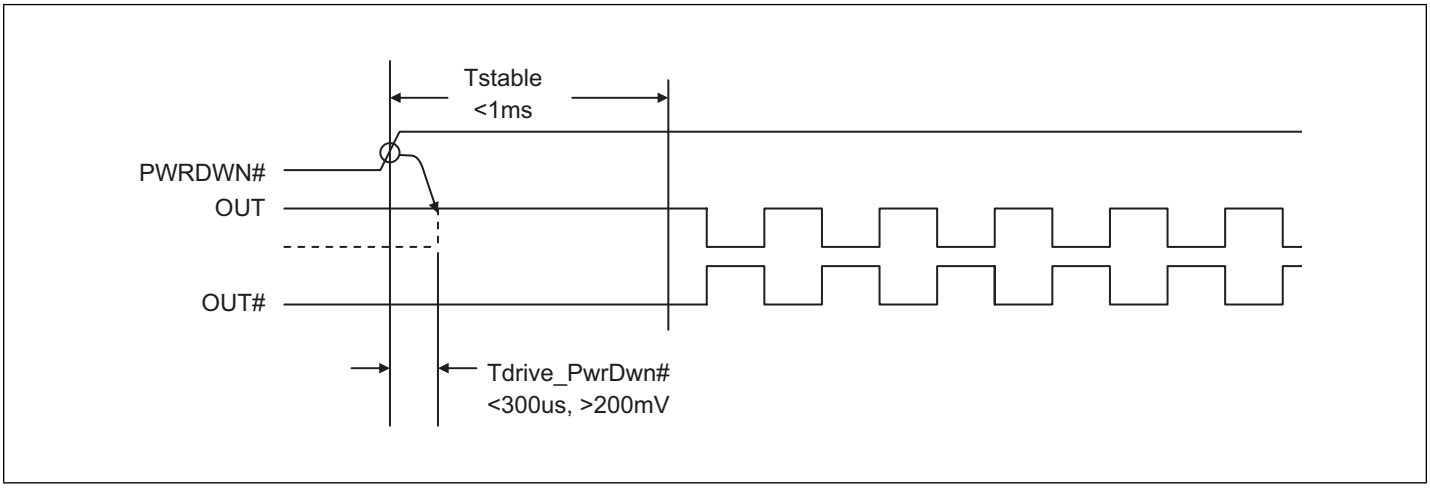
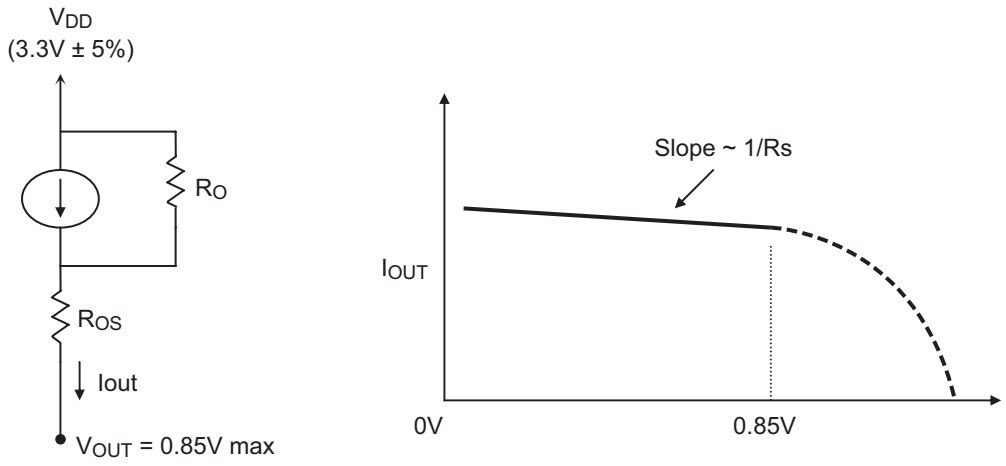


Figure 2. Power down de-assert sequence

Current-mode output buffer characteristics of OUT[0:3], OUT[0:3]#



Differential Clock Buffer characteristics

Symbol	Minimum	Maximum
R_O	3000Ω	N/A
R_{OS}	unspecified	unspecified
V_{OUT}	N/A	850mV

Current Accuracy

Symbol	Conditions	Configuration	Load	Min.	Max.
I_{OUT}	V_{DD} = 3.30 ±5%	R_{REF} = 475Ω 1% I_{REF} = 2.32mA	Nominal test load for given configuration	-12% $I_{NOMINAL}$	+12% $I_{NOMINAL}$

Note:

1. $I_{NOMINAL}$ refers to the expected current based on the configuration of the device.

Differential Clock Output Current

Board Target Trace/Term Z	Reference R, Iref = V_{DD}/(3xRr)	Output Current	V_{OH} @ Z
100Ω (100Ω differential ≈ 15% coupling ratio)	R_{REF} = 475Ω 1%, I_{REF} = 2.32mA	I_{OH} = 6 x I_{REF}	0.7V @ 50

Absolute Maximum Ratings (Over operating free-air temperature range)

Symbol	Parameters	Min.	Max.	Units
V_{DD_A}	3.3V Core Supply Voltage	-0.5	4.6	V
V_{DD}	3.3V I/O Supply Voltage	-0.5	4.6	
V_{IH}	Input High Voltage		4.6	
V_{IL}	Input Low Voltage	-0.5		
Ts	Storage Temperature	-65	150	°C
V_{ESD}	ESD Protection	2000		V
T_J	Junction Temperature		125	°C

Note:

1. Stress beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device.

DC Electrical Characteristics (V_{DD} = 3.3±5%, V_{DD_A} = 3.3±5%)

Symbol	Parameters	Condition	Min.	Max.	Units
V_{DD_A}	3.3V Core Supply Voltage		3.135	3.465	V
V_{DD}	3.3V I/O Supply Voltage		3.135	3.465	
V_{IH}	3.3V Input High Voltage	V_{DD}	2.0	V_{DD} + 0.3	
V_{IL}	3.3V Input Low Voltage		V_{SS} – 0.3	0.8	
I_{IL}	Input Leakage Current	$0 < V_{IN} < V_{DD}$	-5	+5	µA
V_{OH}	3.3V Output High Voltage	I_{OH} = -1mA	2.4		V
V_{OL}	3.3V Output Low Voltage	I_{OL} = 1mA		0.4	
I_{OH}	Output High Current	$I_{OH} = 6 \times I_{REF}$, I_{REF} = 2.32mA	12.2		mA
				15.6	
C_{IN}	Input Pin Capacitance		3	5	pF
C_{OUT}	Output Pin Capacitance			6	
L_{PIN}	Pin Inductance			7	nH
$I_{DD(BYPASS)}$	Power Supply Current (PLL Bypass)	V_{DD} = 3.465V, F_{CPU} = 100MHz		90	mA
I_{DD}	Power Supply Current	V_{DD} = 3.465V	Bypass mode	100	
		F_{CPU} = 100MHz	PLL mode	130	
I_{SS}	Power Down Current	Driven outputs		40	
I_{SS}	Power Down Current	Tristate outputs		12	
T_A	Ambient Temperature		-40	85	°C

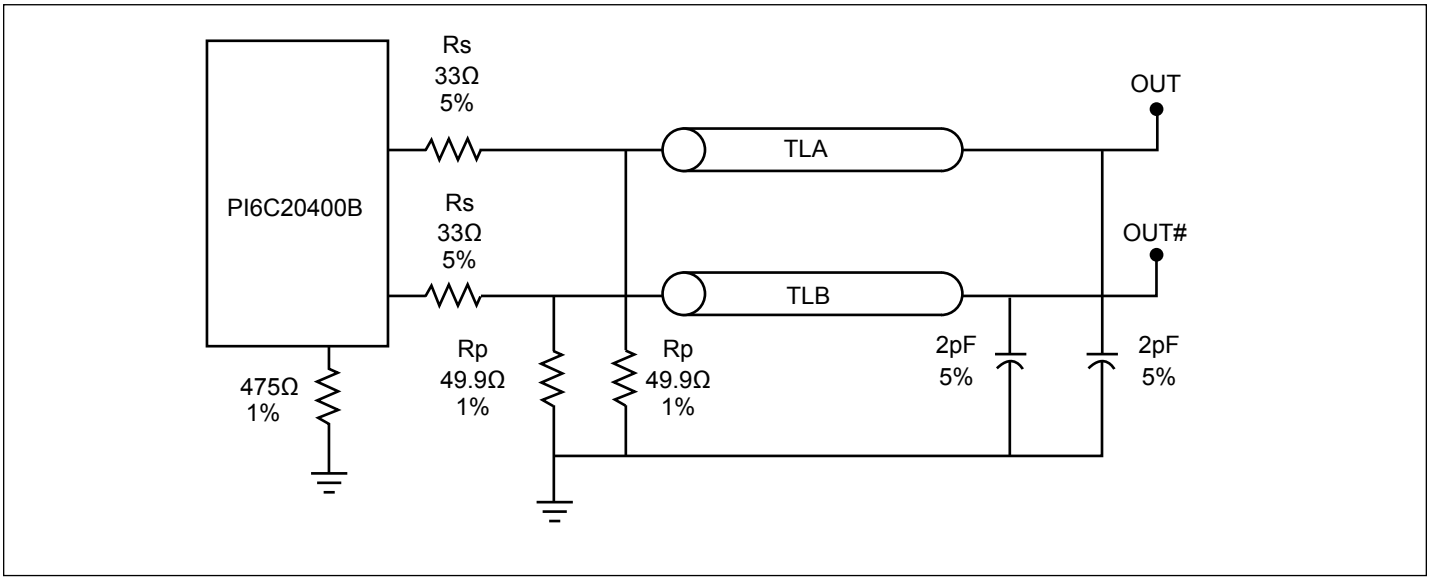
AC Switching Characteristics (V_{DD} = 3.3±5%, V_{DD_A} = 3.3±5%)

Symbol	Parameters	Condition	Min.	Typ.	Max.	Units
F_{IN}	PLL Mode		95		105	MHz
	Bypass Mode		100		400	MHz
T_{rise} / T_{fall} [2]	Rise and Fall Time (measured between 0.175V to 0.525V)		175		700	ps
DT_{rise} / DT_{fall} [2]	Rise and Fall Time Variation				125	ps
T_{pd}	PLL Mode				±250	ps
	Non-PLL Mode		2.5		6.5	ns
T_{jitter} [3, 4]	Cycle – Cycle Jitter				50	ps
V_{HIGH} [2]	Voltage High including overshoot		660		1150	mV
V_{LOW} [2]	Voltage Low including undershoot		-300			mV
V_{cross} [2]	Absolute crossing point voltages		250		550	mV
DV_{cross} [2]	Total Variation of Vcross over all edges				140	mV
T_{DC} [3]	Duty Cycle		45		55	%
$t_{jphPCIeG1}$	Phase Jitter, PLL Mode	PCIe Gen1		30	86	ps (p-p)
$t_{jphPCIeG2}$		PCIE_2_0_8MHz_1_5M_H3_STEP, Low Freq.		0.7	3	ps (rms)
		PCIE_2_0_8MHz_1_5M_H3_STEP, High Freq.		2	3.1	
$t_{jphPCIeG3}$		PCIE_3_0_2MHz_5M_H3_FIRST, Low Freq.		2	3	
		PCIE_3_0_2MHz_5M_H3_FIRST, High Freq.		0.47	1	
$t_{jphPCIeG1}$	Additive Phase Jitter, Bypass Mode	PCIe Gen1		0	0.001	ps (p-p)
$t_{jphPCIeG2}$		PCIE_2_0_8MHz_1_5M_H3_FIRST, Low Freq.		0	0.001	ps (rms)
		PCIE_2_0_8MHz_1_5M_H3_FIRST, High Freq.		0	0.001	
$t_{jphPCIeG3}$		PCIE_3_0_2MHz_5M_H3_FIRST, Low Freq.		0	0.001	
		PCIE_3_0_2MHz_5M_H3_FIRST, High Freq.		0	0.001	

Notes:

1. Test configuration is R_s = 33.2Ω, Rp = 49.9Ω, and 2pF.
2. Measurement taken from Single Ended waveform.
3. Measurement taken from Differential waveform.
4. Measurement taken using M1 data capture analysis tool.
5. Additive jitter is calculated from input and output RMS phase jitter by using PCIe 2.0 filter. (T_{jadd} = √(output jitter)² – (input jitter)²

Configuration Test Load Board Termination



Part Marking

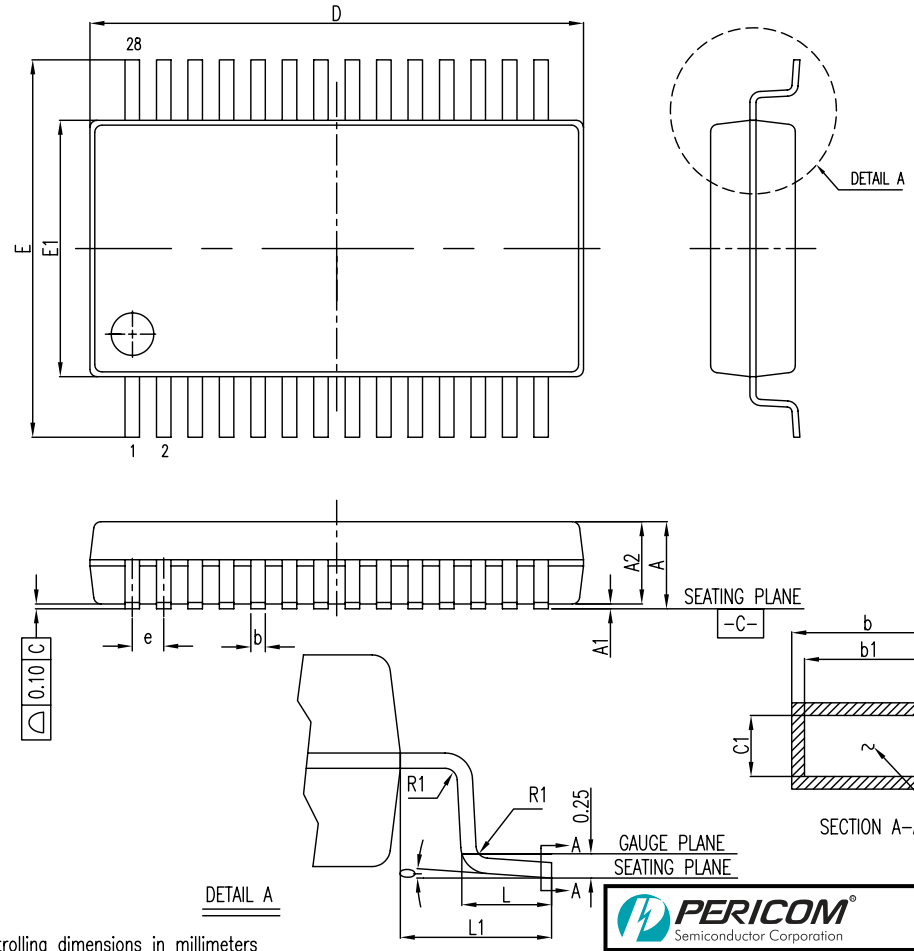
L Package

Y: Die Rev
YY: Year
WW: Workweek
1st X: Assembly Code
2nd X: Fab Code

H Package

Y: Die Rev
YY: Year
WW: Workweek
1st X: Assembly Code
2nd X: Fab Code

Packaging Mechanical: 28-SSOP (H)



SYMBOL	COMMON DIMENSION MILLIMETERS		
	MIN.	NOM.	MAX.
A	--	--	2.0
A1	0.05	--	--
A2	1.65	1.75	1.85
b	0.22	--	0.38
b1	0.22	0.30	0.33
c	0.09	--	0.25
c1	0.09	0.15	0.21
E	7.40	7.80	8.20
E1	5.00	5.30	5.60
D	9.90	10.20	10.50
e	0.65 BSC		
L	0.55	0.75	0.95
L1	1.25 REF.		
R1	0.09	--	--
θ	0°	4°	8°

NOTE:
1. Controlling dimensions in millimeters
2. Ref.: JEDEC MS-150B/AH
3. Package Outline Exclusive of Mold Flash and Metal Burr

PERICOM Semiconductor Corporation

DATE: 04/10/08

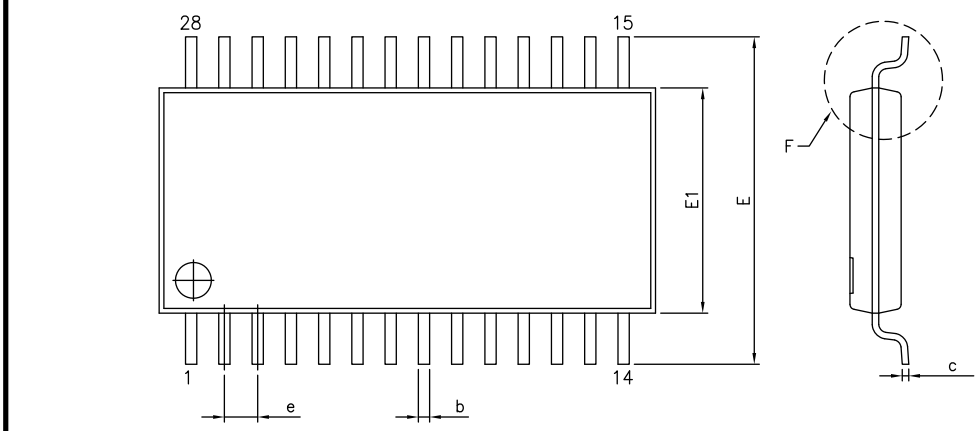
DESCRIPTION: 28-Pin, 209-Mil Wide, SSOP

PACKAGE CODE: H28

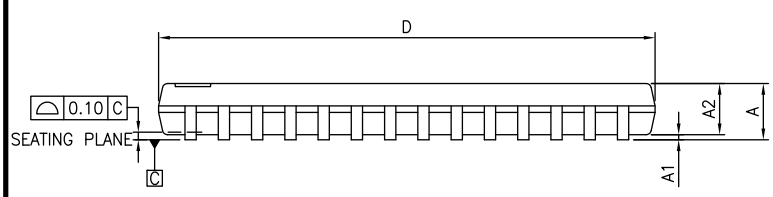
DOCUMENT CONTROL #: PD-1250 **REVISION: F**

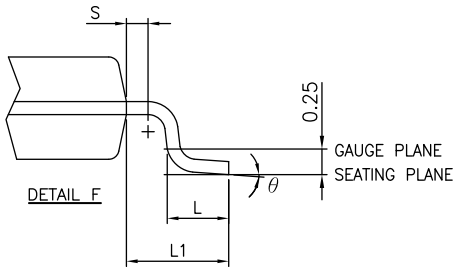
08-0143

Packaging Mechanical: 28-TSSOP (L)



SYMBOLS	MIN.	NOM.	MAX.
A	–	–	1.20
A1	0.05	–	0.15
A2	0.80	1.00	1.05
b	0.19	–	0.30
c	0.09	–	0.20
D	9.60	9.70	9.80
E1	4.30	4.40	4.50
E	6.20	6.40	6.60
e	0.65 BSC		
L1	1.00 REF		
L	0.45	0.60	0.75
S	0.20	–	–
θ	0°	–	8°





NOTES:
1. ALL DIMENSIONS IN MILLIMETERS. ANGLES IN DEGREES.
2. JEDEC MO–153F
3. DIMENSIONS DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

PERICOM Enabling Serial Connectivity

DATE: 03/31/16

DESCRIPTION: 28-Pin, 173mil Wide TSSOP

PACKAGE CODE: L (L28)

DOCUMENT CONTROL #: PD-1313 REVISION: F

16-0076

For latest package info.

please check: http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/

Ordering Information

Ordering Code	Package Code	Package Description
PI6C20400BHEX	H	28-pin, 209-mil wide (SSOP)
PI6C20400BLEX	L	28-pin, 173-mil wide (TSSOP)

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. E = Pb-free and Green
5. X suffix = Tape/Reel

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